

P-channel Enhancement Mode Power MOSFET

Features

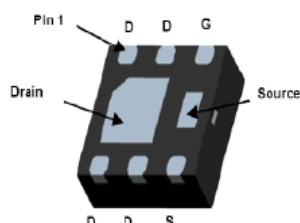
- Halogen free; RoHS compliant
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Pb free plating
- 100% UIS TESTED!
- 100% ΔV_{DS} TESTED!

Applications

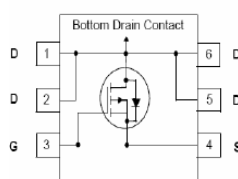
- Load Switch
- PWM Application
- Power Management

Product Summary

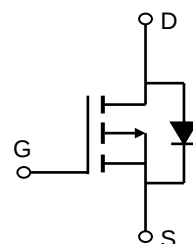
Parameters	Value	Unit
V_{DSS}	-12	V
$V_{GS(th)}_{Typ}$	-0.6	V
$I_D(@V_{GS}=-10V)$	-4.1	A
$R_{DS(ON)}_{Typ} @V_{GS}=-4.5V$	24	$m\Omega$
$R_{DS(ON)}_{Typ} @V_{GS}=-2.5V$	29	$m\Omega$



PDFN2x2-6L Bottom View



Marking



Schematic Diagram

Device	Marking	Package	Packing	Reel Size	Tape Width	Reel (pcs)
ZK17P05E	17P05	DFN2x2	Reel	N/A	N/A	5000

MAXIMUM RATINGS ($T_a=25^{\circ}C$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V_{DS}	-12	V
Gate-Source Voltage		V_{GS}	± 12	V
Continuous Drain Current	$T_C = 25^{\circ}C$	I_D	-4.1	A
	$T_C = 100^{\circ}C$		-2.9	
Pulsed Drain Current		I_{DM}	Refer to Fig.4	A
Power Dissipation		P_D	1.2	W
Thermal Resistance from Junction to Ambient		$R_{\theta JA}$	106	$^{\circ}C/W$
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to 150	$^{\circ}C$

MOSFET ELECTRICAL CHARACTERISTICS

$T_a = 25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Off characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-12			V
Zero gate voltage drain current	I_{DSS}	$V_{DS} = -12V, V_{GS} = 0V$			1.0	μA
Gate-body leakage current	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 12V$			± 100	nA
On characteristics ④						
Gate-threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-0.4	-0.6	-1.0	V
Static drain-source on-sate resistance	$R_{DS(on)}$	$V_{GS} = -4.5V, I_D = -4.1A$		24	31	m Ω
		$V_{GS} = -2.5V, I_D = -3A$		29	38	m Ω
Dynamic characteristics ④ ⑤						
Input capacitance	C_{iss}	$V_{DS} = -6V, V_{GS} = 0V$ f =1MHz		1010		pF
Output capacitance	C_{oss}			130		
Reverse transfer capacitance	C_{rss}			106		
Switching characteristics ④ ⑤						
Total gate charge	Q_g	$V_{GS} = 0 \text{ to } -4.5V$ $V_{DS} = -6V, I_D = -2A$		10		nC
Gate-source charge	Q_{gs}			2		
Gate-drain charge	Q_{gd}			1		
Turn-on delay time	$t_{d(on)}$	$V_{DD} = -6V, I_D = -2A$ $V_{GS} = -10V, R_{GEN} = 2.7\Omega$		5		ns
Turn-on rise time	t_r			12		
Turn-off delay time	$t_{d(off)}$			50		
Turn-off fall time	t_f			23		
Drain-Source Diode Characteristics						
Drain-source diode forward voltage	V_{SD} ④	$V_{GS} = 0V, I_S = -4.1A$			1.2	V
Continuous drain-source diode forward current	I_S ①				-4.1	A
Pulsed drain-source diode forward current	I_{SM} ②				-16	A
Reverse recovery time	t_{rr}	$di/dt = 60A/\mu s, I_F = -2A$		9		ns
Reverse recovery charge	Q_{rr}			1.3		nC

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
2. R θ JA is measured with the device mounted on a minimum recommended pad of 2oz copper FR4 PCB.
3. R θ JA is measured with the device mounted on a 1inch² pad of 2oz copper FR4 PCB.
4. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 0.5\%$.

Typical Performance Characteristics

Figure 1: Power De-rating

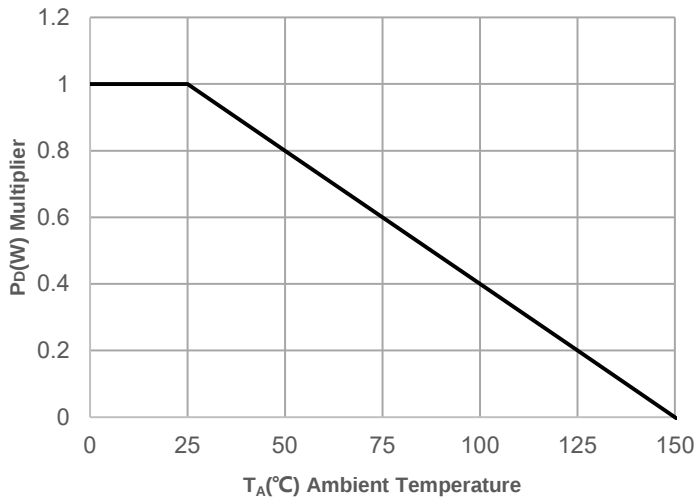


Figure 2: Current De-rating

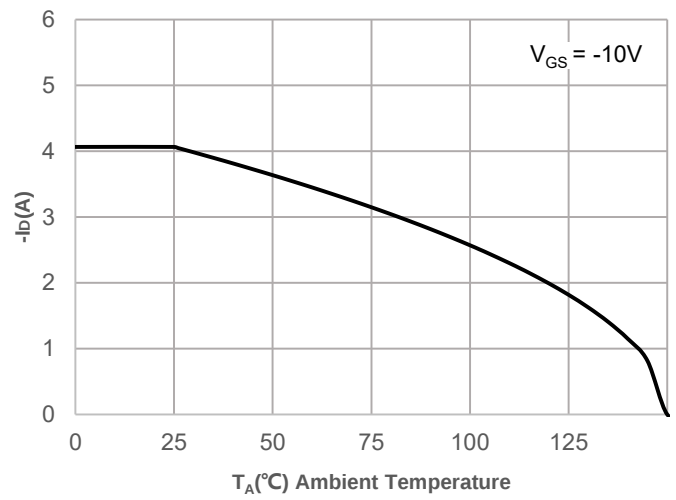


Figure 3: Normalized Maximum Transient Thermal Impedance

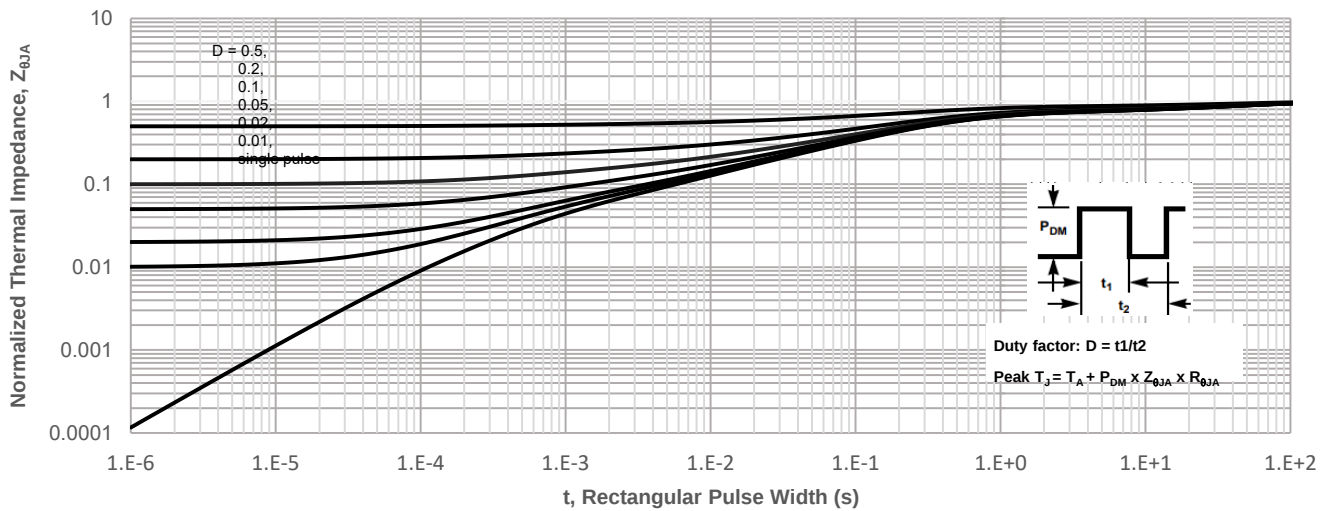
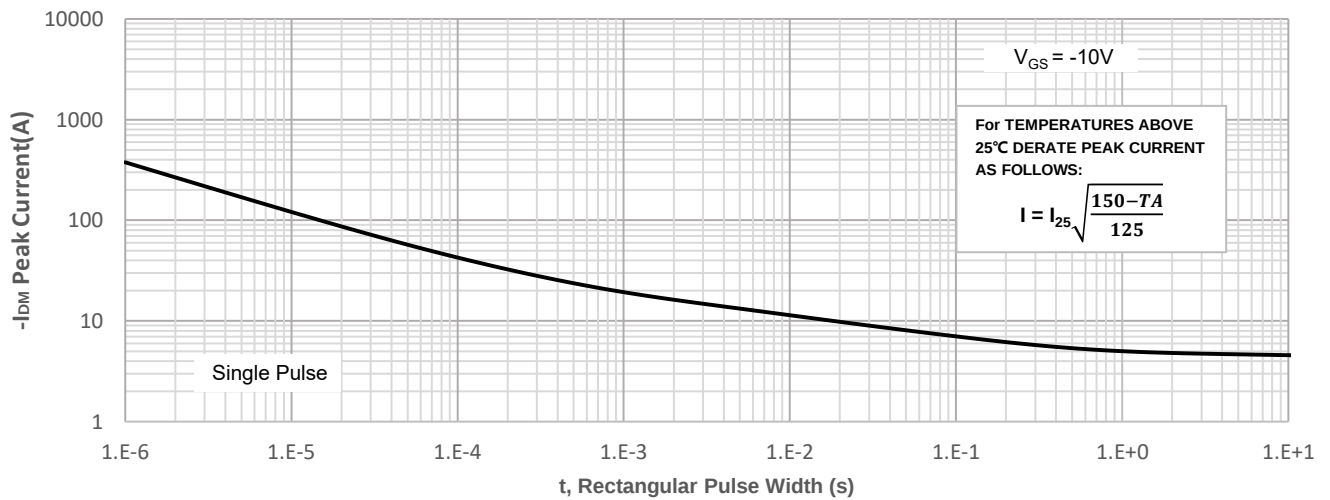


Figure 4: Peak Current Capacity



Typical Performance Characteristics

Figure 5: Output Characteristics

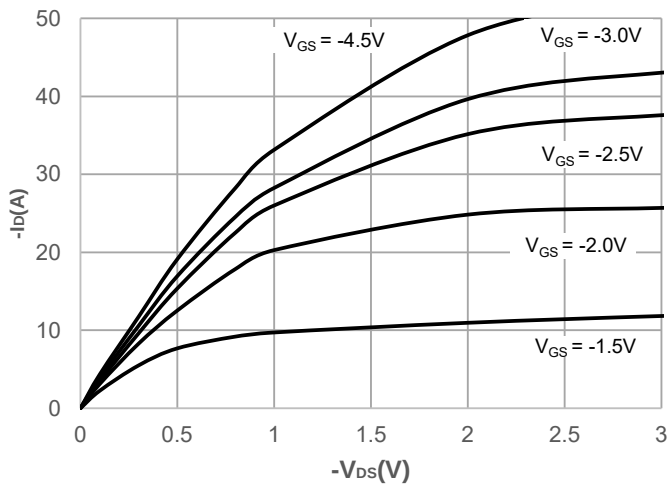


Figure 6: Typical Transfer Characteristics

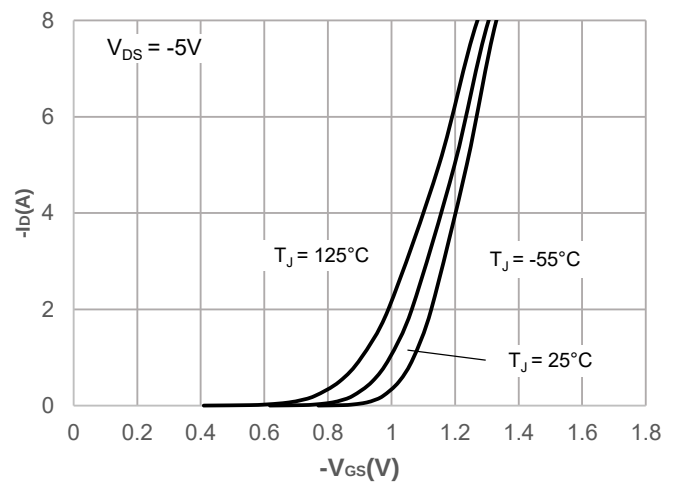


Figure 7: On-resistance vs. Drain Current

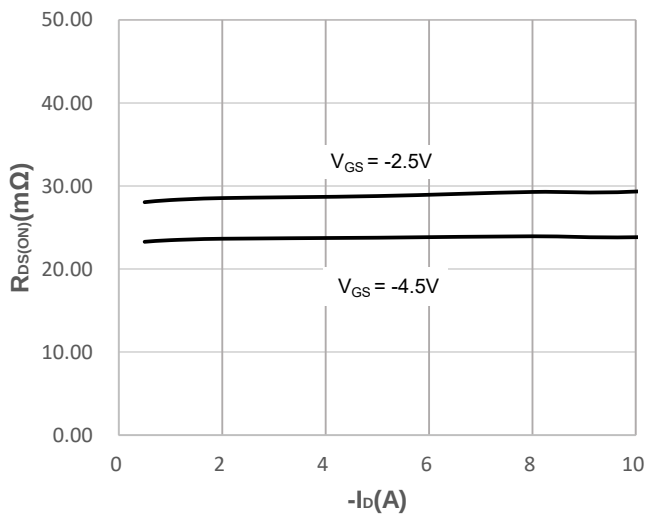


Figure 8: Body Diode Characteristics

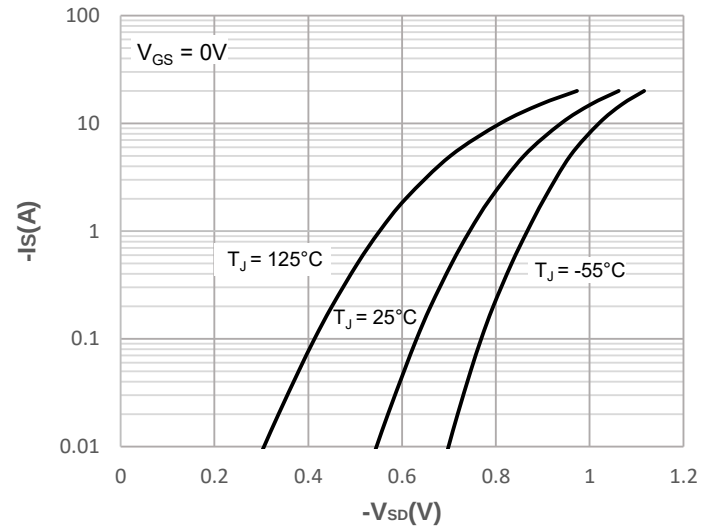


Figure 9: Gate Charge Characteristics

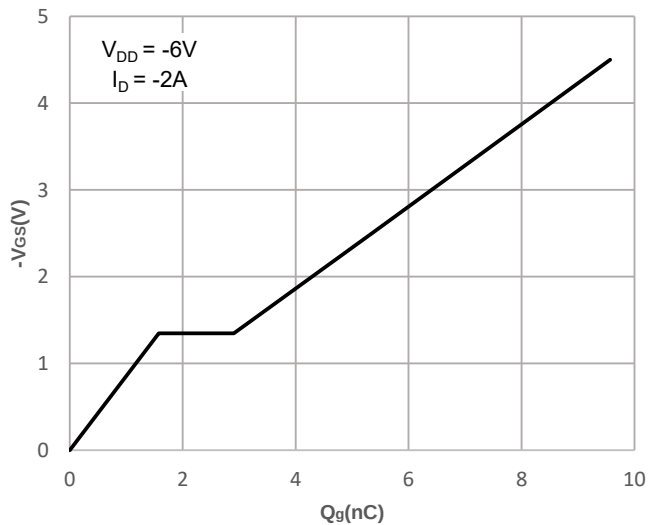
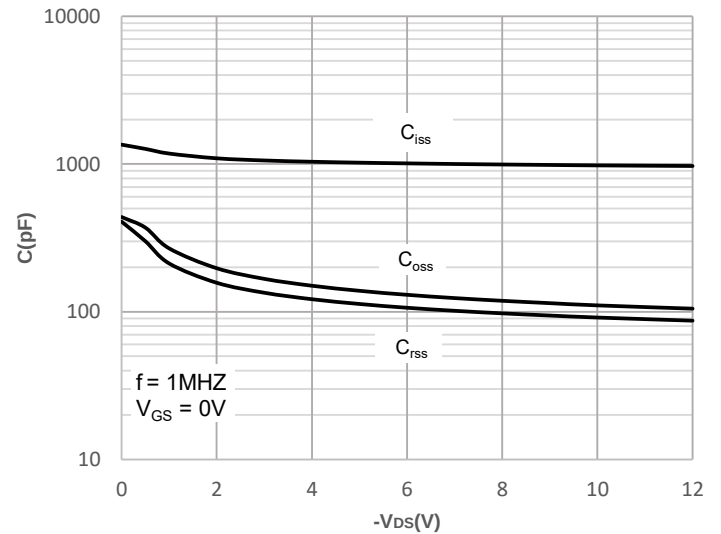


Figure 10: Capacitance Characteristics



Typical Performance Characteristics

Figure 11: Normalized Breakdown voltage vs. Junction Temperature

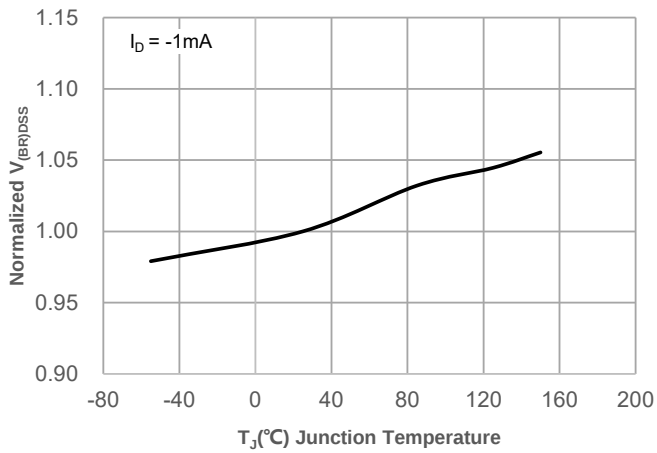


Figure 12: Normalized on Resistance vs. Junction Temperature

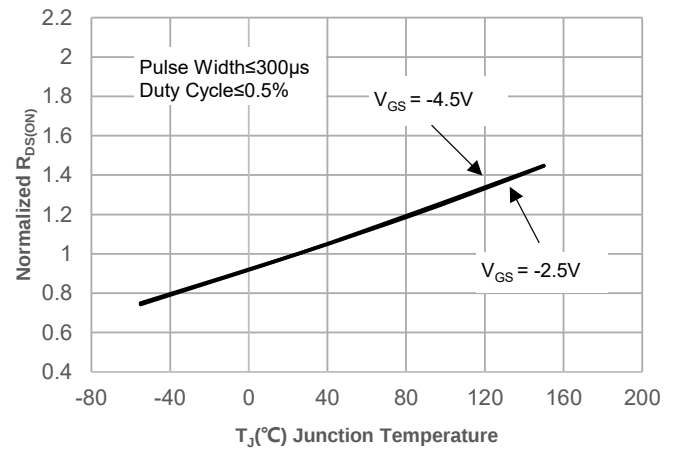


Figure 13: Normalized Threshold Voltage vs. Junction Temperature

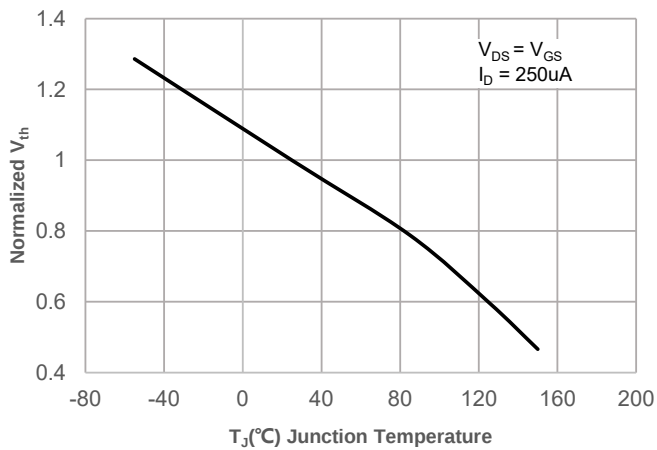


Figure 14: $R_{DS(ON)}$ vs. V_{GS}

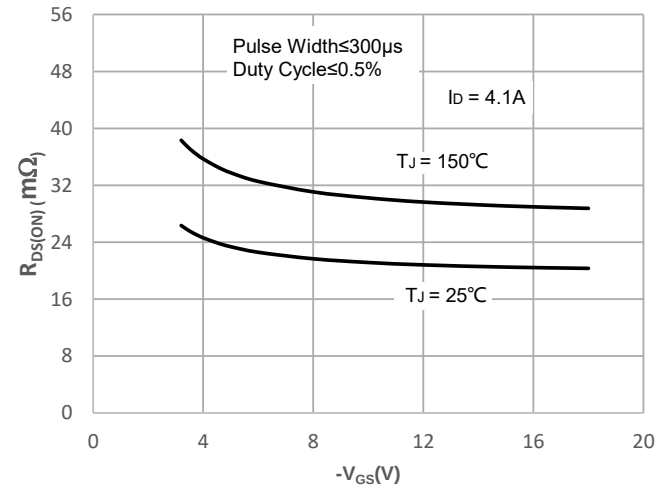
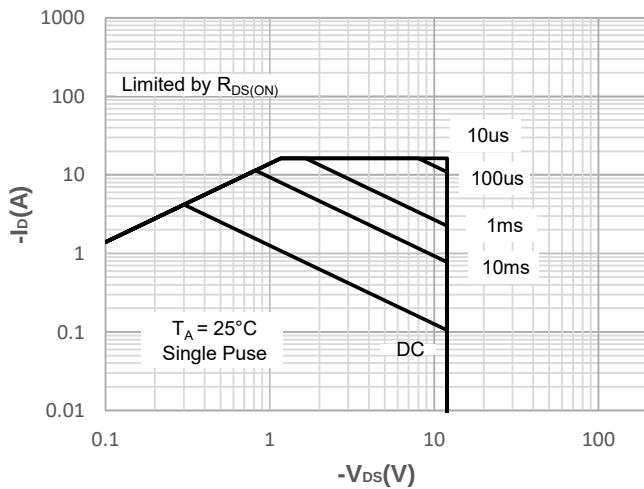


Figure 15: Maximum Safe Operating Area



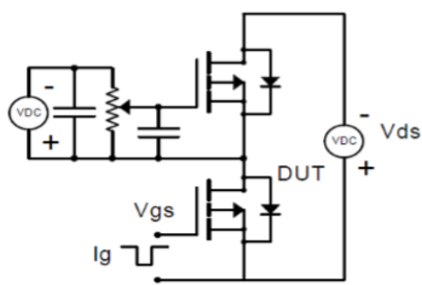


Figure 1: Gate Charge Test Circuit & Waveform

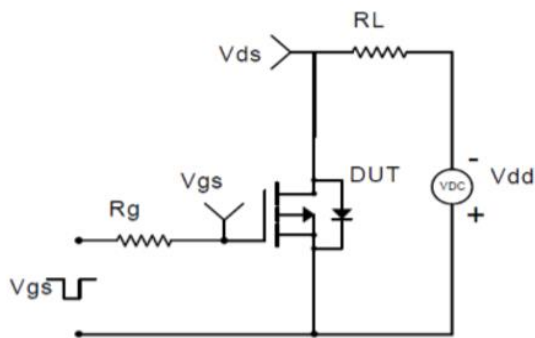


Figure 2: Resistive Switching Test Circuit & Waveform

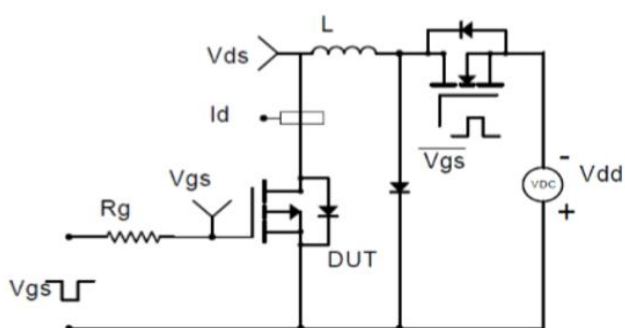


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

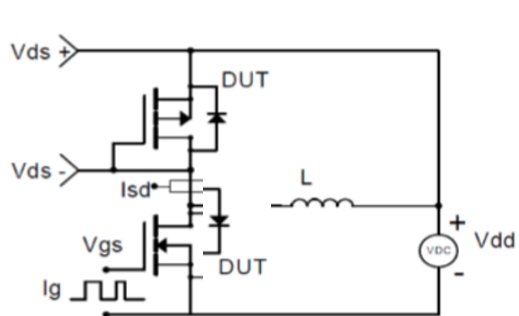
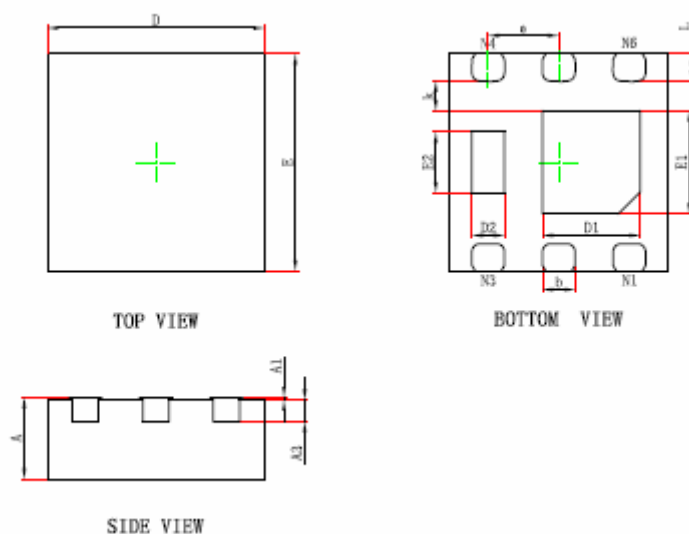


Figure 4: Diode Recovery Test Circuit & Waveform



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A3	0.203REF.		0.008REF.	
D	1.924	2.076	0.076	0.082
E	1.924	2.076	0.076	0.082
D1	0.800	1.000	0.031	0.039
E1	0.850	1.050	0.033	0.041
D2	0.200	0.400	0.008	0.016
E2	0.460	0.660	0.018	0.026
k	0.200MIN.		0.008MIN.	
b	0.250	0.350	0.010	0.014
e	0.650TYP.		0.026TYP.	
L	0.174	0.326	0.007	0.013